

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claims 3 and 7 and ADD new claims 9 and 10 in accordance with the following:

1. (ORIGINAL) A semiconductor device characterized in that
connection pads for wire bonding are arranged at peripheral regions of an electrode terminal formation surface of a semiconductor chip,
test pads for testing the semiconductor chip are arranged in an inside region surrounded by said peripheral regions of said electrode terminal formation surface, and
a plurality of rewiring patterns extend from the peripheral regions to said inside region of said electrode terminal formation surface and the individual rewiring patterns connect the individual electrode terminals and the corresponding connection pads and test pads.
2. (ORIGINAL) A semiconductor device as set forth in claim 1, characterized in that the test pads are arranged in an array on said inside region.
3. (CURRENTLY AMENDED) A semiconductor device as set forth in claim 1-~~or~~2, characterized in that said electrode terminals are exposed from openings of a protective insulation layer covering said electrode terminal formation surface, said rewiring patterns extend on said protective insulation layer and are connected to said electrode terminals via said openings, said rewiring patterns and said protective insulation layer are further covered by an insulation layer, and said connection pads and said test pads connected to said rewiring patterns are exposed from openings of said insulation layer.

4. (ORIGINAL) A semiconductor device comprised of one or a stack of a plurality of the semiconductor device as set forth in any one of claims 1 to 3 as an element semiconductor device or a stack of one or more of each of said element semiconductor device and a semiconductor chip carried on a wiring board, said semiconductor device characterized in that connection pads of each said element semiconductor device and connection electrodes of said wiring board are connected by wire bonding, and each said element semiconductor device and/or each said semiconductor chip is sealed by resin on said wiring board.

5. (ORIGINAL) An interposer characterized in that connection pads for wire bonding to be connected to a wiring board are arranged at peripheral regions of one surface of the interposer for carrying a semiconductor chip, test pads for testing the semiconductor chip are arranged in an inside region surrounded by said peripheral regions of said one surface or the other surface, and a plurality of rewiring patterns extend from said peripheral regions to said inside region and the individual rewiring patterns connect the corresponding connection pads and test pads.

6. (ORIGINAL) An interposer as set forth in claim 5, characterized in that said test pads are arranged in an array in said inside region.

7. (CURRENTLY AMENDED) A semiconductor device comprised of a semiconductor module, comprised of an interposer as set forth in claim 5-~~or~~6, on the surface of which opposite to the surface where said test pads are arranged, one or a plurality of said semiconductor chips are stacked, carried on a wiring board, said semiconductor device characterized in that connection pads of said interposer and connection electrodes of said wiring board are connected by wire bonding, and said semiconductor module is sealed by resin on said wiring board.

8. (ORIGINAL) A semiconductor device as set forth in claim 7, characterized in that a semiconductor module where a surface where said test pads are formed is exposed and a semiconductor chip carrying surface of the interposer is sealed by a resin.

9. (NEW) A semiconductor device as set forth in claim 2, characterized in that said electrode terminals are exposed from openings of a protective insulation layer covering said electrode terminal formation surface, said rewiring patterns extend on said protective insulation layer and are connected to said electrode terminals via said openings, said rewiring patterns and said protective insulation layer are further covered by an insulation layer, and said connection pads and said test pads connected to said rewiring patterns are exposed from openings of said insulation layer.

10. (NEW) A semiconductor device comprised of a semiconductor module, comprised of an interposer as set forth in claim 6, on the surface of which opposite to the surface where said test pads are arranged, one or a plurality of said semiconductor chips are stacked, carried on a wiring board,
said semiconductor device characterized in that
connection pads of said interposer and connection electrodes of
said wiring board are connected by wire bonding, and
said semiconductor module is sealed by resin on said wiring
board.